

## TM40N04DF

## N-Channel Enhancement Mosfet

### General Description

- Low  $R_{DS(ON)}$
- RoHS and Halogen-Free Compliant

### Applications

- Load switch
- PWM

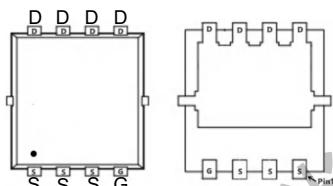
### General Features

$V_{DS} = 40\text{ V}$   $I_D = 40\text{ A}$   
 $R_{DS(ON)} = 7.4\text{ m}\Omega$  (typ.) @  $V_{GS} = 10\text{ V}$

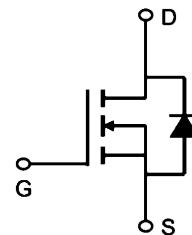
100% UIS Tested  
100%  $R_g$  Tested



DF:PDFN3x3-8L



Marking: 40N04



### Absolute Maximum Ratings ( $T_c = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{ V}$	40	A
$I_D @ T_c = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{ V}$	22.1	A
$I_{DM}$	Pulsed Drain Current	140	A
$P_D @ T_c = 25^\circ\text{C}$	Total Power Dissipation	44	W
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 175	$^\circ\text{C}$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	---	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	2.8	$^\circ\text{C/W}$

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**Electrical Characteristics:** ( $T_c=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	40	---	---	V
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=40\text{V}, T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=32\text{V}, T_J=85^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	1.2	1.6	2.0	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$	---	7.4	10	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=4\text{A}$	---	10	13	
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=2\text{A}$	---	13	---	S
<b>Dynamic Characteristics</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$	---	1205	2180	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	128	245	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	52	106	
$R_{\text{g}}$	Gate resistance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=0\text{V}, f=1\text{MHz}$	---	2.2	---	$\Omega$
<b>Switching Characteristics</b>						
$t_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=15\text{V}, V_{\text{GS}}=10\text{V}$ $R_{\text{G}}=3.3 \Omega, I_{\text{D}}=1\text{A}$	---	13.2	25	ns
$t_{\text{r}}$	Rise Time		---	2.2	5	ns
$t_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	72	130	ns
$t_{\text{f}}$	Fall Time		---	4.5	10	ns
$Q_{\text{g}}$	Total Gate Charge		---	19.7	30	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=20\text{V}, V_{\text{GS}}=10\text{V}, I_{\text{D}}=8\text{A}$	---	2.8	4.2	nC
$Q_{\text{gd}}$	Gate-Drain "Miller" Charge		---	5.1	7.6	nC

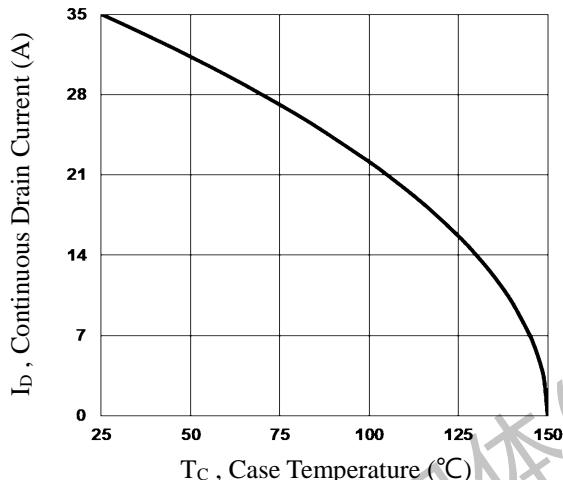
**TM40N04DF****N-Channel Enhancement Mosfet**

Drain-Source Diode Characteristics						
$I_S$	Contiuos Source Current	$V_G=V_D=0V$ , Force Current	---	---	40	A
$I_{SM}$	Pulsed Source Current		---	---	70	A
$V_{SD}$	Source-Drain Diode Forward Voltage	$V_{GS}=0V$ , $I_S=1A$ , $T_J=25^\circ C$	---	---	1	V
$t_{rr}$	Reverse Recovery Time	$I_S=1A$ , $dI/dt=100A/\mu s$ ,	---	17	---	nS
$Q_{rr}$	Reverse Recovery Charge	$T_J=25^\circ C$ , $V_{GS}=0V$	---	2.8	---	nC

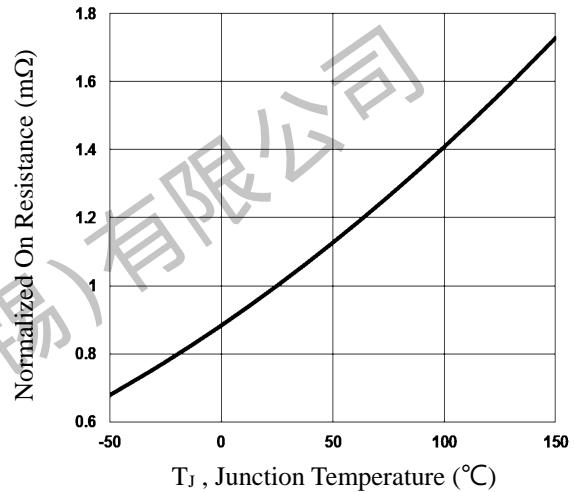
## **TM40N04DF**

## **N-Channel Enhancement Mosfet**

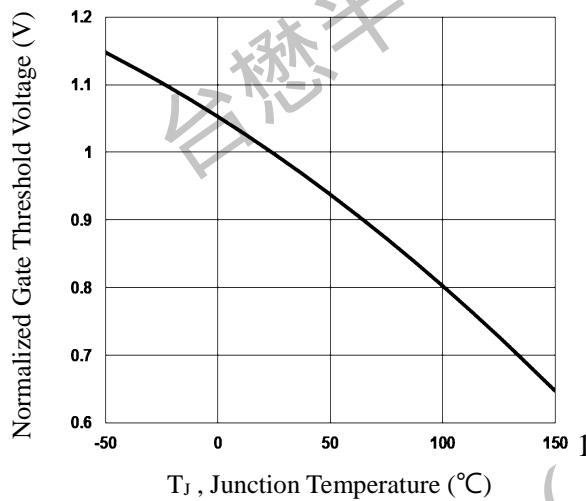
**Typical Characteristics:** ( $T_c=25^\circ\text{C}$  unless otherwise noted)



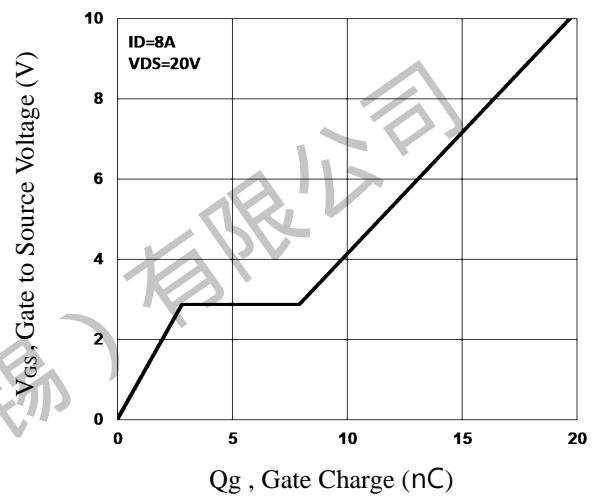
**Fig.1 Continuous Drain Current vs. Tc**



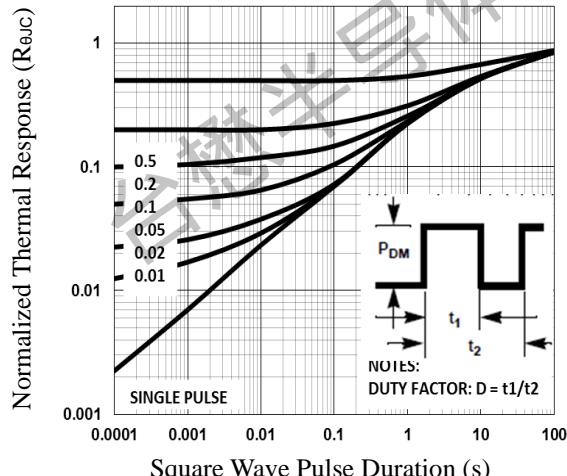
**Fig.2 Normalized RDS(on) vs. Tj**



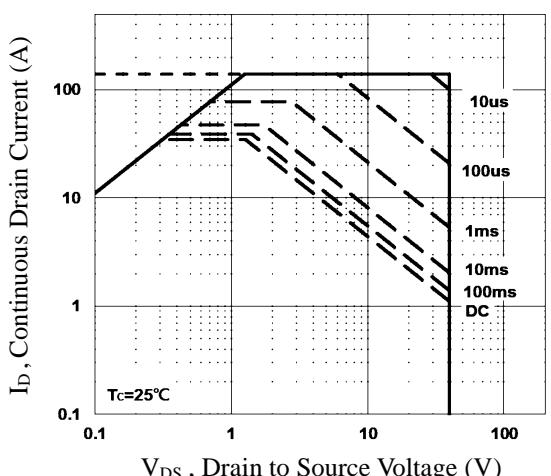
**Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>**



**Fig.4 Gate Charge Waveform**



**Fig.5 Normalized Transient Impedance**

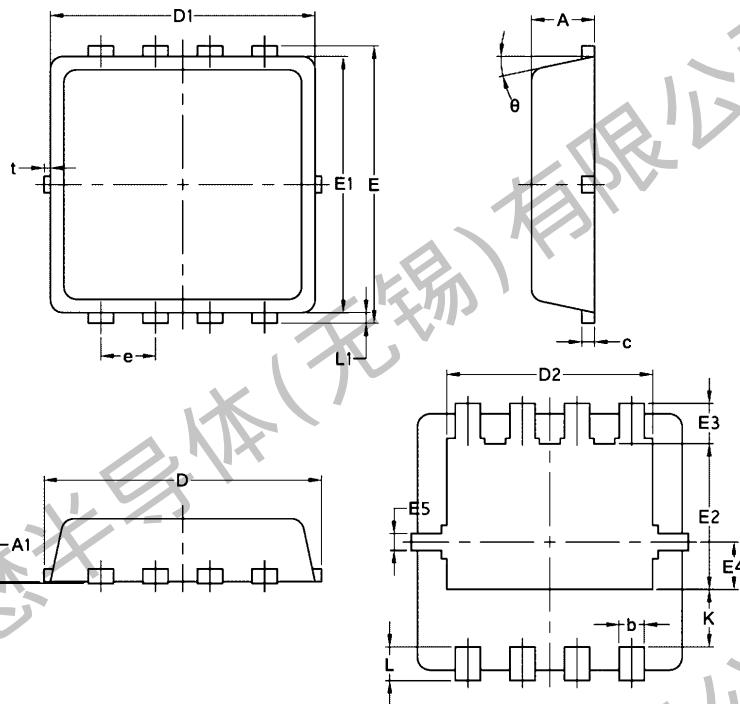


**Fig.6 Maximum Safe Operation Area**

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**Package Mechanical Data: DFN3x3-8L**

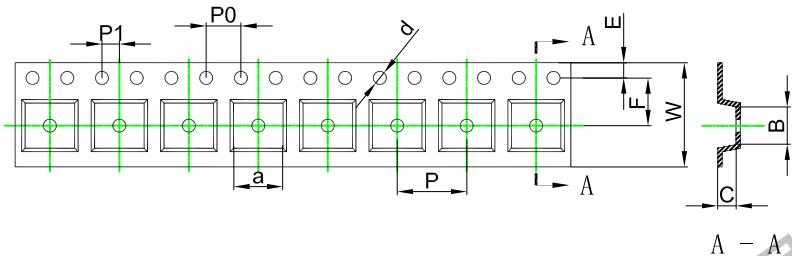


Symbol	Common mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14

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### **PDFN3x3-8L Embossed Carrier Tape**



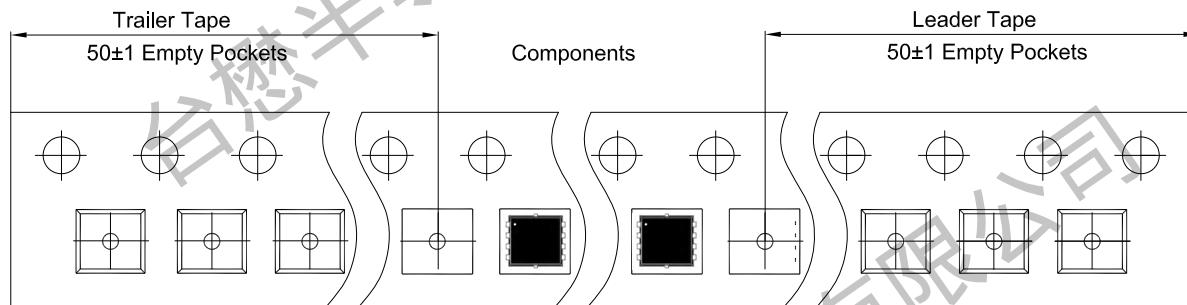
#### Packaging Description:

SOP-8L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 33cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

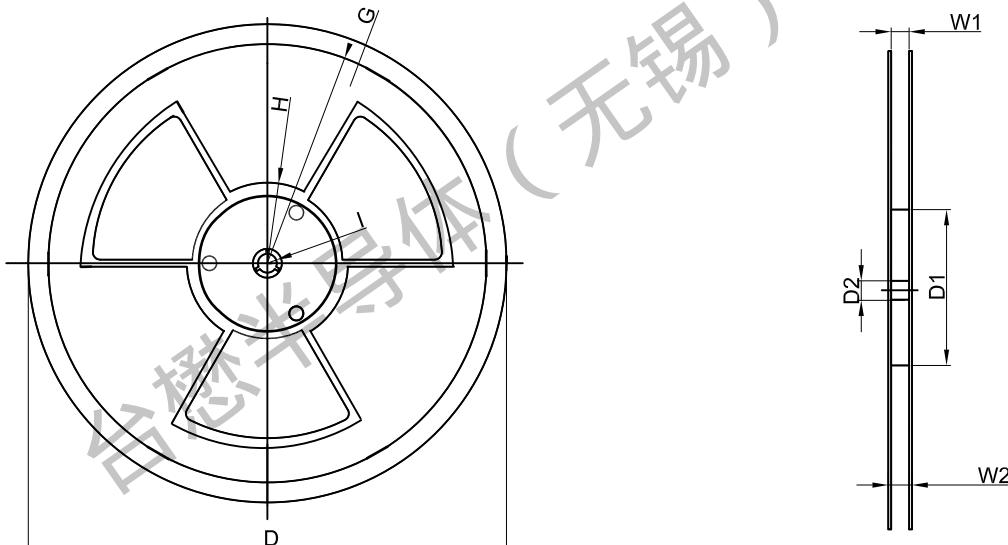
ALL DIM IN mm

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
PDFN3x3-8L	6.40	5.40	2.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00

### **PDFN3x3-8L Tape Leader and Trailer**



### **PDFN3x3-8L Reel**



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
13" Dia	Ø330.00	100.00	13.00	R135.00	R55.00	R6.50	12.00	14.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
5,000 pcs	13 inch	10,000 pcs	370×355×52	50,000 pcs	400×360×368	

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#### Revision history:

Date	Rev	Description	Page
2023.05.10	23.05	Original	